

CDSF355 (Lead-free Device)

High Speed



Features

Designed for mounting on small surface.

Extremely thin/leadless package.

Low leakage current.

High mounting capability, strong surge withstand, high reliability.

Mechanical data

Case: 1005(2512) standard package,

molded plastic.

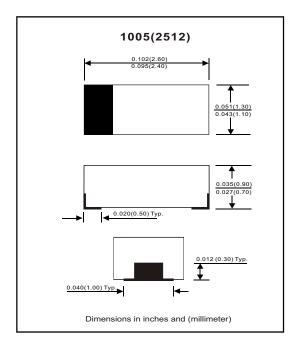
Terminals: Gold plated, solderable per

MIL-STD-750, method 2026.

Polarity: Indicated by cathode band.

Mounting position: Any

Weight: 0.006 gram(approx.).



Maximum Rating (at TA=25°C unless otherwise noted)

Parameter	Conditions	Symbol	Min	Тур	Max	Unit
Repetitive peak reverse voltage		VRRM			90	V
Reverse voltage		VR			80	V
Average forward current		lo			100	mA
Forward current,surge peak	8.3 ms single half sine-wave superimposed on rate load (JEDEC method)	lfsm		1000		mA
Repetitive peak forward current		IFRM			225	mA
Power Dissipation		PD			300	mW
Storage temperature		Тѕтс	-40		+125	°C
Junction temperature		Tj			+125	°C

Electrical Characteristics (at TA=25°C unless otherwise noted)

Parameter	Conditions	Symbol	Min	Тур	Max	Unit
Forward voltage	IF = 100 mA DC	VF			1.0	V
Reverse current	V _R = 80 V	lr			0.1	uA
Capacitance between terminals	f = 1 MHz,and 0.5VDC reverse voltage	Ст		3		рF
Reverse recovery time	$V_R = 6V$, $I_F = 10$ mA, $R_L = 50$ ohms	Trr		4		nS

REV:A

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RATING AND CHARACTERISTIC CURVES (CDSF355)

Fig. 1 - Forward characteristics

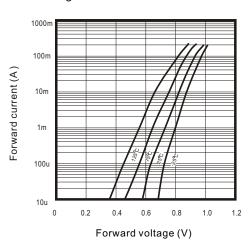


Fig. 3 - Capacitance between terminals characteristics

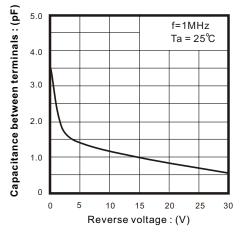


Fig. 2 - Reverse characteristics

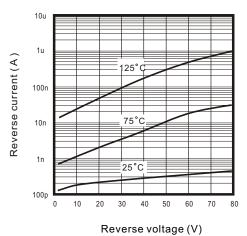


Fig. 4 - Current derating curve

